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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/721,787	11/26/2003	Harry Hedler	543822002200	4141	
25227	7590 06/05/2006		EXAMINER		
	& FOERSTER LLP		PERKINS, PAMELA E		
1650 TYSON SUITE 300	S BOULEVARD		ART UNIT	PAPER NUMBER	
MCLEAN, VA 22102			2822		
			DATE MAILED: 06/05/200	6	

Please find below and/or attached an Office communication concerning this application or proceeding.

## Advisory Action Before the Filing of an Appeal Brief

Application No.	Applicant(s)	
10/721,787	HEDLER ET AL.	
Examin r	Art Unit	
Pamela E. Perkins	2822	

	Famela L. Ferkins	2022							
The MAILING DATE of this communicati n appe	ars on the cover sheet with the	correspondence add	ress						
THE REPLY FILED 09 May 2006 FAILS TO PLACE THIS APPLICATION IN CONDITION FOR ALLOWANCE.									
this application, applicant must timely file one of the follow places the application in condition for allowance; (2) a No a Request for Continued Examination (RCE) in compliance time periods:	The reply was filed after a final rejection, but prior to or on the same day as filing a Notice of Appeal. To avoid abandonment of this application, applicant must timely file one of the following replies: (1) an amendment, affidavit, or other evidence, which places the application in condition for allowance; (2) a Notice of Appeal (with appeal fee) in compliance with 37 CFR 41.31; or (3) a Request for Continued Examination (RCE) in compliance with 37 CFR 1.114. The reply must be filed within one of the following								
a) The period for reply expiresmonths from the mailing									
b) The period for reply expires on: (1) the mailing date of this Advisory Action, or (2) the date set forth in the final rejection, whichever is later. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the mailing date of the final rejection.  Examiner Note: If box 1 is checked, check either box (a) or (b). ONLY CHECK BOX (b) WHEN THE FIRST REPLY WAS FILED WITHIN									
TWO MONTHS OF THE FINAL REJECTION. See MPEP 70									
Extensions of time may be obtained under 37 CFR 1.136(a). The date on which the petition under 37 CFR 1.136(a) and the appropriate extension fee have been filed is the date for purposes of determining the period of extension and the corresponding amount of the fee. The appropriate extension fee under 37 CFR 1.17(a) is calculated from: (1) the expiration date of the shortened statutory period for reply originally set in the final Office action; or (2) as set forth in (b) above, if checked. Any reply received by the Office later than three months after the mailing date of the final rejection, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).  NOTICE OF APPEAL									
2. The Notice of Appeal was filed on A brief in comp	liance with 37 CFR 41.37 must be	filed within two month	ns of the date of						
filing the Notice of Appeal (37 CFR 41.37(a)), or any extension thereof (37 CFR 41.37(e)), to avoid dismissal of the appeal. Since a Notice of Appeal has been filed, any reply must be filed within the time period set forth in 37 CFR 41.37(a).  AMENDMENTS									
3. The proposed amendment(s) filed after a final rejection,	but prior to the date of filing a brief	f, will <u>not</u> be entered b	ecause						
(a) They raise new issues that would require further co		TE below);							
(b) They raise the issue of new matter (see NOTE belo									
(c) ☐ They are not deemed to place the application in bet appeal; and/or			the issues for						
(d) They present additional claims without canceling a	corresponding number of finally re	jected claims.							
NOTE: (See 37 CFR 1.116 and 41.33(a)).	OA O O O O O O O O O O O O O O O O O O		(DTOL 004)						
4. The amendments are not in compliance with 37 CFR 1.1.		ompliant Amendment	(PTOL-324).						
5. Applicant's reply has overcome the following rejection(s)									
<ol> <li>Newly proposed or amended claim(s) would be al non-allowable claim(s).</li> </ol>	lowable if submitted in a separate	, timely filed amendme	ent canceling the						
7. For purposes of appeal, the proposed amendment(s): a)		ill be entered and an e	explanation of						
how the new or amended claims would be rejected is pro-	vided below or appended.								
The status of the claim(s) is (or will be) as follows: Claim(s) allowed:									
Claim(s) allowed Claim(s) objected to:									
Claim(s) rejected:									
Claim(s) withdrawn from consideration:									
AFFIDAVIT OR OTHER EVIDENCE									
<ol> <li>The affidavit or other evidence filed after a final action, bu because applicant failed to provide a showing of good and was not earlier presented. See 37 CFR 1.116(e).</li> </ol>									
9. The affidavit or other evidence filed after the date of filing entered because the affidavit or other evidence failed to determine the control of the con	a Notice of Appeal, but prior to the	e date of filing a brief,	will <u>not</u> be						
showing a good and sufficient reasons why it is necessary									
10. ☐ The affidavit or other evidence is entered. An explanation REQUEST FOR RECONSIDERATION/OTHER	•		•						
11.  The request for reconsideration has been considered bu See Continuation Sheet.	t does NOT place the application	in condition for allowa	nce because:						
12. Note the attached Information Disclosure Statement(s).	(PTO/SB/08 or PTO-1449) Paper_	No(s). <u>5/9/06</u>	. ^						
13. Other:	2	alan Si	XL.						
	$\rightarrow$	Zandra V. Smith							
	dina	rvisory Patent Exa	miner						
	Supe	02 20 0-	<b>~</b> -						
	•	Zandra V. Smith rivisory Patent Exe 23 May 20	<del>20</del> 0						

Continuation of 11. does NOT place the application in condition for allowance because: prior art Henle does teach printing electrical lines on main sides of the semiconductor chips such that the lines run from contact points of the semiconductor chips beyond lower edges of the main sides onto base sides of the semiconductor chip. Although it is not specifically taught in the spefication, figure 1 of Henle show lines running from contact points of the semiconductor chips beyond lower edges of the main sides onto base sides of the semiconductor chip. Also, Examiner pointed to cloumn 8, lines 20-31 to teach lines running from contact points of the semiconductor chips beyond lower edges of the main sides onto base sides of the semiconductor chip. In addition, column 7, lines 34-48 teach lines running from contact points of the semiconductor chips beyond lower edges of the main sides onto base sides of the semiconductor chip. Kinsman does disclose partially encapsulating the semiconductor devices, one of the semiconductor device is encapulated. During patent examination, the claims are given the broadest reasonable interpretation consistent with the specification. See In re Morris, 127 F.3d 1048, 44 USPQ2d 1023 (Fed. Cir. 1997). See MPEP § 2111 - § 2116.01 for case law pertinent to claim analysis.